



## Material Content Data Sheet



<b>Sales Product Name</b>		IFX21004TN V51		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA000921376						
<b>Package</b>		PG-TO220-5-12		<b>Weight*</b>		2155.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.055	0.14	0.14	1417	1417
leadframe	non noble metal	iron	7439-89-6	0.923	0.04		428	
	inorganic material	phosphorus	7723-14-0	0.277	0.01		128	
	non noble metal	copper	7440-50-8	921.567	42.76	42.81	427503	428059
wire	non noble metal	aluminium	7429-90-5	0.274	0.01	0.01	127	127
encapsulation	organic material	carbon black	1333-86-4	1.215	0.06		564	
	plastics	epoxy resin	-	55.882	2.59		25923	
	inorganic material	silicondioxide	60676-86-0	550.312	25.53	28.18	255283	281770
leadfinish	non noble metal	tin	7440-31-5	23.910	1.11	1.11	11092	11092
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		4	
	non noble metal	nickel	7440-02-0	3.285	0.15	0.15	1524	1528
solder	noble metal	silver	7440-22-4	0.119	0.01		55	
	non noble metal	tin	7440-31-5	0.095	0.00		44	
	non noble metal	lead	7439-92-1	4.539	0.21	0.22	2106	2205
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		82	
	non noble metal	iron	7439-89-6	0.590	0.03		274	
	non noble metal	copper	7440-50-8	589.466	27.34	27.38	273446	273802
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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